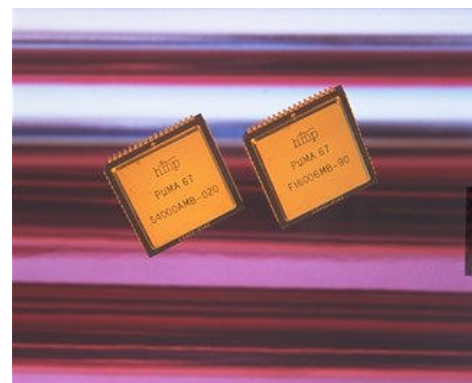
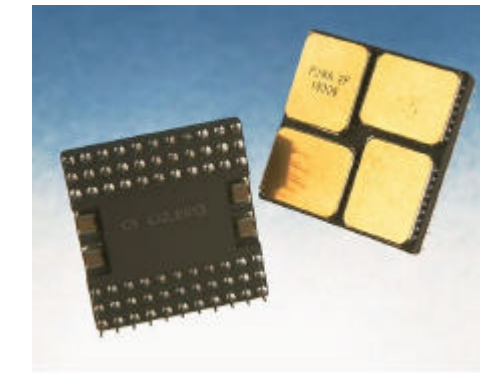
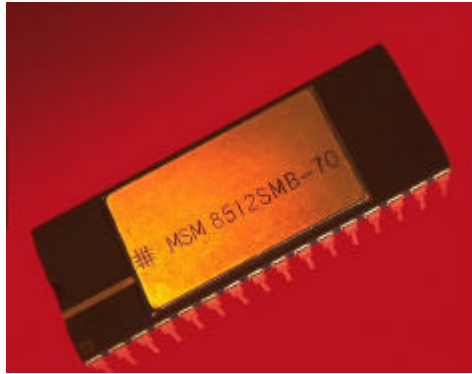


Part Numbering



M S M 8512 SC X L MB - 10



1. TECHNOLOGY

The memory technology is represented by a single character:-

S	Static RAM	FLASH	Flash EEPROM
D	Dynamic RAM	V	Video DRAM
E	EEPROM	P	Pseudostatic RAM
U	UVEPROM	M	Microsystem

2. FAMILY

Describes whether the product is Monolithic or a Module:

M	Monolithic	blank	Module
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3. ORGANISATION

Indicates the overall organisation of the memory product, the format is:-

8 512

Data Path Width Memory Array Depth in Kbytes

4. PACKAGE TYPE

The following table indicates the package type identifiers.

Motherboard	Monolithic	SOIC (Plastic)	LCC (Ceramic)
Other DIP Ceramic	B	BK	BC
0.6" DIP Ceramic	S	SK	SC
0.4" DIP Ceramic	K	KK	KC
0.3" DIP Ceramic	T	TK	TC
0.1" DIP Ceramic	V	VK	VC
LCC Ceramic	W	-	-
JLCC Ceramic	J	-	-
Flatpack	G	-	-
SIP Ceramic	C	-	-
DIP FR4 (Plastic)	-	FK	FC

5. PINOUT ARRANGEMENT

This field identifies the mechanical arrangement of the device pinout:-

blank	JEDEC compatible
E	EPROM compatible (on SRAM modules only)
X	ASIC defined, this is the first of two characters, the second is a reference used by the vendor to identify the pinout.

6. POWER CONSUMPTION

The modules power consumption mode is defined within this field:

blank	Standard power (arbitrary standard power parts with CMOS or Bipolar logic)
L	Low power (4T low power parts with CMOS logic)
U	Ultra Low power (6T low power parts with CMOS logic)

7. TEMPERATURE AND SCREENING

The operating temperature and screening levels are indicated by this field:

blank	Commercial	(0°C to +70°C)
I	Industrial	(-40°C to +85°C)
M	Military	(-55°C to +125°C)
MB	Screened in accordance with MIL-STD-883C	

8. ASIC DESIGNS / CUSTOMER SPECIFICATIONS

All part numbers for these products will be designated by the Engineering Department.

SPEED

Either two or three characters are used to denote access time in nanoseconds:

025	=	20ns (<35ns start with a zero)
70	=	70ns
10	=	100ns

PUMA2 S 2000 L MB - 10



PRODUCT DESIGNATOR

PUMA2	=	66 pin Ceramic PGA Package
PUMA3	=	66 pin Plastic PGA Package
PUMA67	=	68 J-Leaded Surface Mount Ceramic Package
PUMA68	=	68 J-Leaded Surface Mount PLCC
PUMA77	=	68 leaded Gull Wing Surface Mount Package

1. TECHNOLOGY

The memory technology is represented by a single character:

S	Static RAM		
F	Flash EEPROM		
E	EEPROM	U	UVEPROM

2. DEVICE CAPACITY

The total memory array capacity, in Kbits, is indicated within this field.

3. POWER CONSUMPTION

The PUMA power consumption mode is defined within this field:

blank	Standard power
L	Low power

4. TEMPERATURE AND SCREENING

The operating temperature and screening levels are indicated by this field:

blank	Commercial	(0°C to +70°C)
I	Industrial	(-40°C to +85°C)
M	Military	(-55°C to +125°C)
MB	Screened in accordance with MIL-STD-883C	



Military Products Shortform Guide

Organisation	Generic	Packages	Speed (ns)
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MONOLITHIC SRAM

32K x 8 SRAM	MSM832	JLCC, LCC	20-35
32K x 8 SRAM	MSM832	DIL, SKINNY DIP	70-150
128K x 8 SRAM	MSM8128	JLCC, LCC	20-35
128K x 8 SRAM	MSM8128	DIL	70-120
512K x 8 SRAM	MSM8512	JLCC	20-35
512K x 8 SRAM	MSM8512	DIL	70-100

MONOLITHIC FLASH

128K x 8	MFM8126	JLCC, DIL	70-120
512K x 8	MFM8516	JLCC, DIL	70-120

PUMA SRAM MODULE

1Mbit 32K x 32	PUMA2S1000	PGA	20-45
4Mbit 128K x 32	PUMA**S4000	PGA, JLCC, Gullwing	20-35
16Mbit 512K x 32	PUMA**S16000	PGA, GULLWING	20-35

PUMA FLASH MODULE

4Mbit 128K x 32	PUMA**F4006	PGA	70-120
16Mbit 512K x 32	PUMA**F16006	PGA, GULLWING	70-120

PUMA EEPROM MODULE

1Mbit 32K x 32	PUMA2E1000	PGA	70-120
4Mbit 128K x 32	PUMA**4001	PGA, JLCC, Gullwing	120-200

HIGH RELIABILITY PLASTIC SRAM

4Mbit 128K x 32	PUMA68S4000	PLCC	20-35
16Mbit 512K x 32	PUMA68S16000	PLCC	20-35

HIGH RELIABILITY PLASTIC FLASH

16Mbit 512K x 32	PUMA68F16006	PLCC	70-120
32Mbit 1M x 32	PUMA68F32006	PLCC	120-20
64Mbit 2M x 32	PUMA68F64006	PLCC	120-200

Rev 4